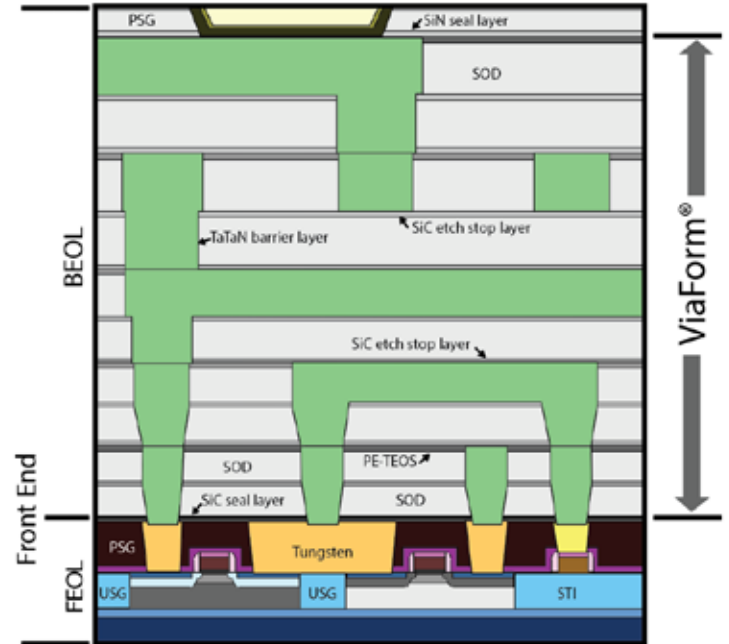


# ViaForm® Series Materials

## Advanced Copper Plating Technology

- **Custom solution packages based on the latest ViaForm® products through close customer collaborations.**
- **ViaForm® solutions capable of meeting manufacturing needs of the most advanced processing nodes.**
- **Pioneering Advanced Cu technologies proven uniform interconnect fill and superior reliability.**
- **Best-in-class product quality and manufacturing capability recognized by the industry.**



MacDermid Enthone ViaForm® copper damascene chemistries deliver superior filling performance for wafer fabrication. Each chemistry is specially designed for manufacturing advanced copper interconnects and provides a high degree of process control. It enables robust interconnect fill capability and ensures superior device yield and reliability.

The key characteristics include fast and void-free fill with broad operating window, excellent overburden control and across wafer uniformity, as well as customized impurities to meet reliability needs for specific applications.

ViaForm chemistry is produced in MacDermid Enthone's high volume manufacturing (HVM) facility and advanced research facilities based in West Haven, Connecticut, USA. The HVM features computer integrated manufacturing including fully automated, enclosed chemical distribution and dedicated processing streams. It ensures stringent batch-to-batch control and consistency, readily meeting the demanding manufacturing requirements worldwide.

ViaForm offers a clear advantage in that it meets the demands of shrinking device geometries while giving chip manufacturers the flexibility to apply this chemistry to their existing processes and tool systems. This is especially important in the manufacturing of memory and logic devices when new generation process technology demands higher degree of process control, more robust interconnect fill performance and greater device reliability.

ViaForm chemistry is exclusively marketed and distributed worldwide by Entegris, Inc. Entegris also provides technical field support during qualification and HVM at customer's sites.



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